AMENDMENTS TO THE CLAIMS

1-11. (Cancelled)

12. (Currently Amended) A heat-dissipating fin module comprising:

a heat-conductive base, which is installed on a heat-generating component of an electronic device;

a plurality of first heat-dissipating fins, which are vertically installed at intervals on one half side of the heat-conductive base, each of the first heat-dissipating fins having an arc surface parallel to one another, and the space between adjacent first heat-dissipating fins forming a first airflow space for providing a curved airflow path;

a plurality of second heat-dissipating fins, which are vertically installed at intervals on the other half side of the heat-conductive base, each of the second heat-dissipating fins having an arc surface parallel to one another but having curvature centers opposite to those of the first heat-dissipating fins, and the space between adjacent second heat-dissipating fins forming a second airflow space for providing a curved airflow path that does not cross the airflow path of the first airflow space; ~~and~~

at least one third heat-dissipating fin, which is vertically installed on the heat-conductive base in an outer region between the first heat-dissipating fins and the second heat-dissipating fins; and

wherein, the curvature centers of the first heat-dissipating fins and the second heat-dissipating fins are on a same line, the outermost first heat-dissipating fin and second heat-dissipating fin are shorter, and the third heat-dissipating fin is straight.

13-17. (Cancelled)

18. (Original) The heat-dissipating fin module of claim 12, wherein the first heat-dissipating fins, the second heat-dissipating fins, and the third heat-dissipating fins are formed on the heat-conductive base by cutting and squeezing.